

P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY

| V_{DS} (V) | $R_{DS(on)}$ (Ω) | I_D (A) | Q_g (Typ.) |
|--------------|-----------------------------|-----------|--------------|
| - 20 | 0.065 at $V_{GS} = - 4.5$ V | - 5 | 4.5 nC |
| | 0.105 at $V_{GS} = - 2.5$ V | - 4.1 | |

FEATURES

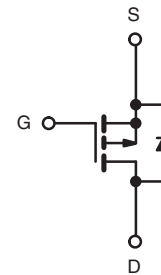
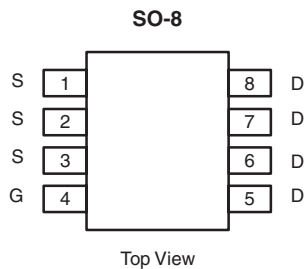
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- PWM Optimized, Low Q_{gd}/Q_{gs} Ratio



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Step-Down Converter for HDD Applications
- Portable Asynchronous DC-DC



Ordering Information: Si4803DY-T1-E3 (Lead (Pb)-free)
Si4803DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

| Parameter | Symbol | Limit | Unit |
|--|----------------|-----------------------|------|
| Drain-Source Voltage | V_{DS} | - 20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | |
| Continuous Drain Current ($T_J = 150$ °C) | $T_C = 25$ °C | - 5 | A |
| | $T_C = 70$ °C | - 4 | |
| | $T_A = 25$ °C | - 4 ^{a, b} | |
| | $T_A = 70$ °C | - 3.1 ^{a, b} | |
| Pulsed Drain Current | I_{DM} | - 20 | |
| Continuous Source-Drain Diode Current | $T_C = 25$ °C | - 2.6 | |
| | $T_A = 25$ °C | 1.6 ^{a, b} | |
| Avalanche Current | I_{AS} | 5 | |
| Single-Pulse Avalanche Energy | E_{AS} | 1.25 | mJ |
| Maximum Power Dissipation | $T_C = 25$ °C | 3.0 | W |
| | $T_C = 70$ °C | 1.9 | |
| | $T_A = 25$ °C | 2 ^{a, b} | |
| | $T_A = 70$ °C | 1.2 ^{a, b} | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to 150 | °C |

THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Typical | Maximum | Unit |
|---|------------|---------|---------|------|
| Maximum Junction-to-Ambient ^{a, c} | R_{thJA} | 52 | 62.5 | °C/W |
| Maximum Junction-to-Foot | R_{thJF} | 35 | 42 | |

Notes:

- Surface mounted on 1" x 1" FR4 board.
- $t = 10$ s.
- Maximum under Steady State conditions is 110 °C/W.

| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | |
|---|--------------------------------------|--|-------|--------|-------|-------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = - 250 μA | - 20 | | | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | I _D = - 250 μA | | - 20 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | ΔV _{GS(th)} /T _J | | | 3 | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = - 250 μA | - 0.6 | | - 1.5 | V |
| Gate-Source Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 12 V | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 20 V, V _{GS} = 0 V | | | - 1 | μA |
| | | V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C | | | - 10 | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ - 10 V, V _{GS} = - 4.5 V | - 10 | | | A |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 3.5 A | | 0.052 | 0.065 | Ω |
| | | V _{GS} = - 2.5 V, I _D = - 3 A | | 0.085 | 0.105 | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = - 10 V, I _D = - 3.5 A | | 10 | | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz | | 480 | | pF |
| Output Capacitance | C _{oss} | | | 132 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 55 | | |
| Total Gate Charge | Q _g | V _{DS} = - 10 V, V _{GS} = - 10 V, I _D = - 5 A | | 9.7 | 14.5 | nC |
| | | V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 5 A | | 4.5 | 7 | |
| Q _{gs} | | | 1 | | | |
| Q _{gd} | | | 1 | | | |
| Gate Resistance | R _g | f = 1 MHz | | 7.5 | 15 | Ω |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = - 10 V, R _L = 2 Ω I _D ≡ - 5 A, V _{GEN} = - 10 V, R _g = 1 Ω | | 4 | 8 | ns |
| Rise Time | t _r | | | 10 | 20 | |
| Turn-Off DelayTime | t _{d(off)} | | | 16 | 30 | |
| Fall Time | t _f | | | 8 | 16 | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = - 10 V, R _L = 2 Ω I _D ≡ - 5 A, V _{GEN} = - 4.5 V, R _g = 1 Ω | | 20 | 35 | |
| Rise Time | t _r | | | 50 | 90 | |
| Turn-Off DelayTime | t _{d(off)} | | | 16 | 30 | |
| Fall Time | t _f | | | 10 | 20 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 2.6 | A |
| Pulse Diode Forward Current | I _{SM} | | | | - 20 | |
| Body Diode Voltage | V _{SD} | I _S = - 1 A, V _{GS} = 0 V | | - 0.75 | - 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | I _F = - 3.5 A, dI/dt = 100 A/μs, T _J = 25 °C | | 25 | 38 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 11.25 | 17 | nC |
| Reverse Recovery Fall Time | t _a | | | 9 | | ns |
| Reverse Recovery Rise Time | t _b | | | 16 | | |

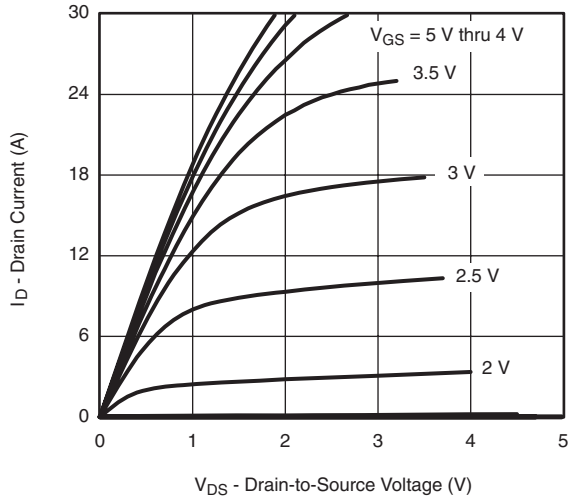
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

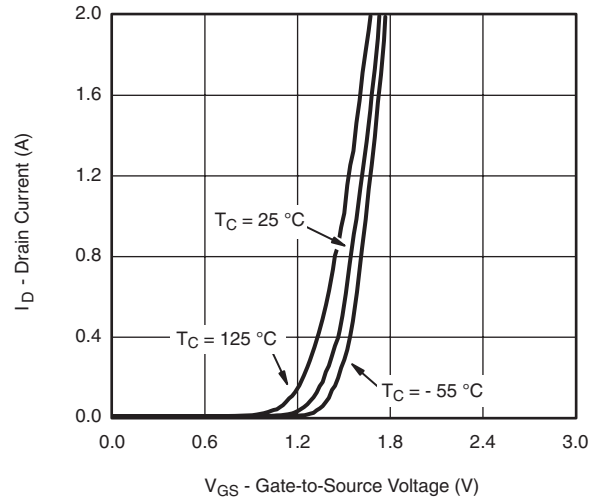
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

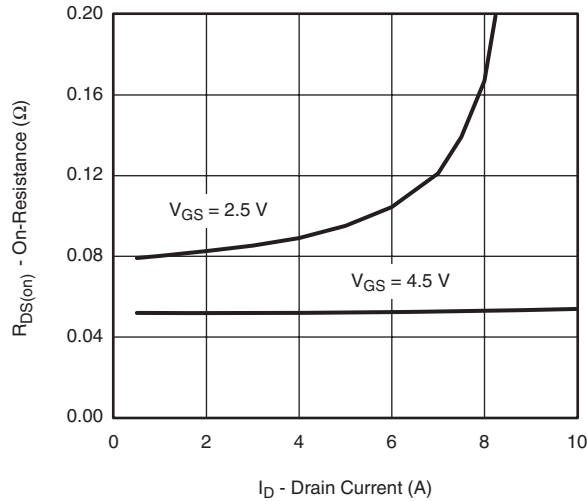
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



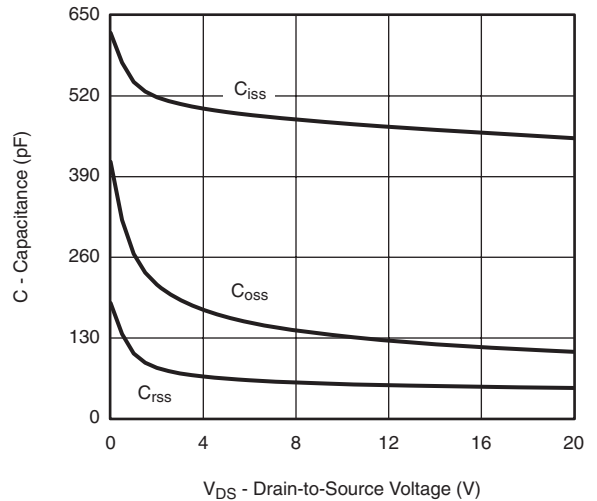
Output Characteristics



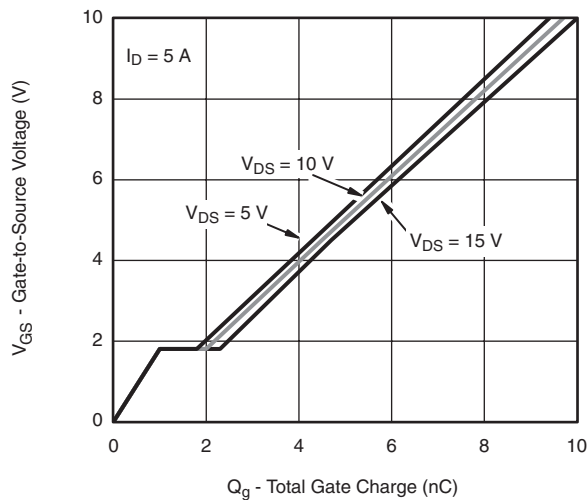
Transfer Characteristics



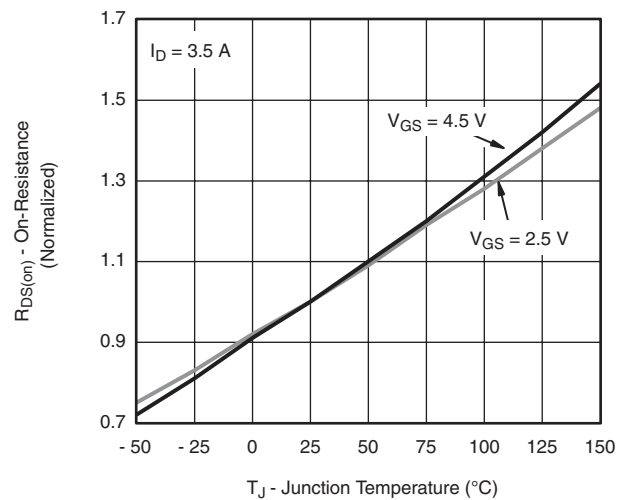
On-Resistance vs. Drain Current



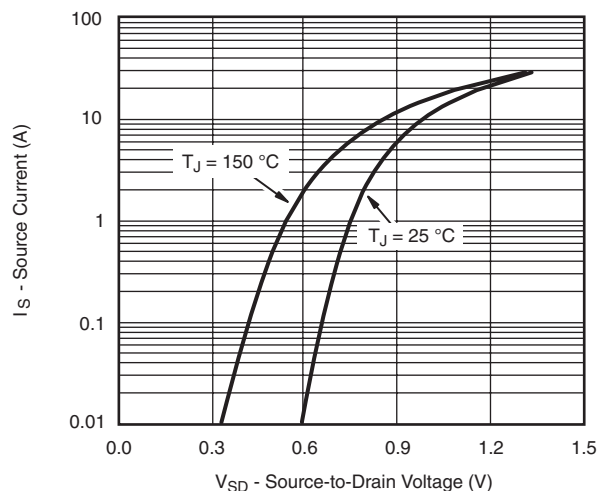
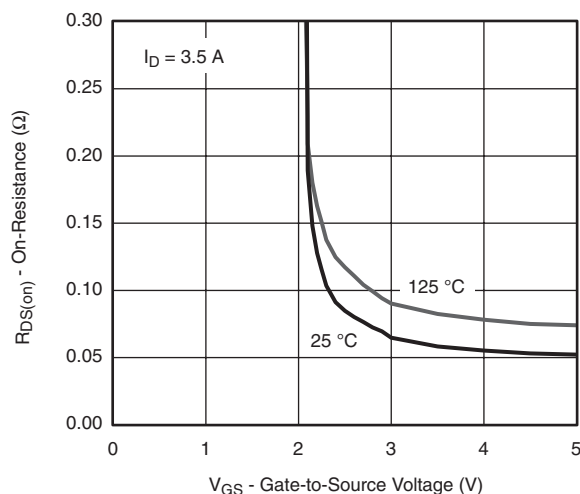
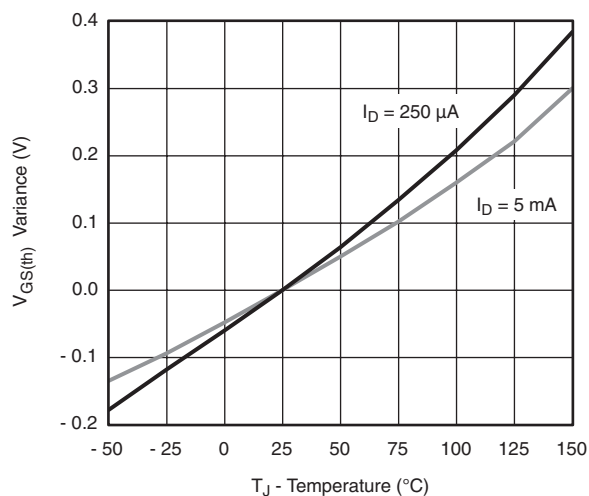
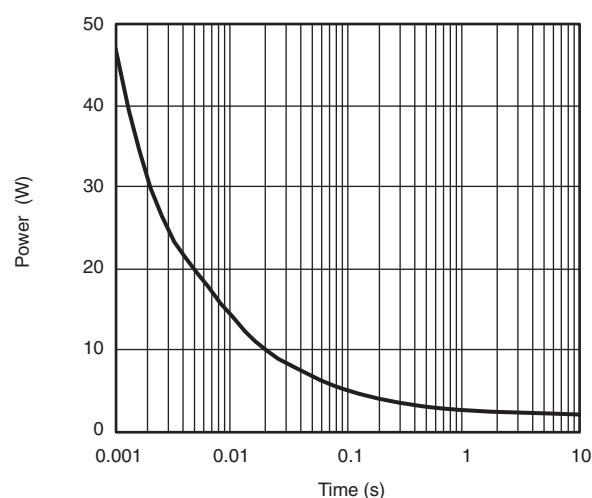
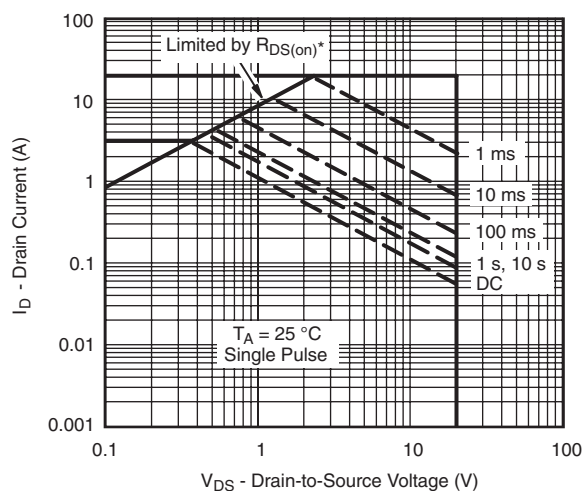
Capacitance



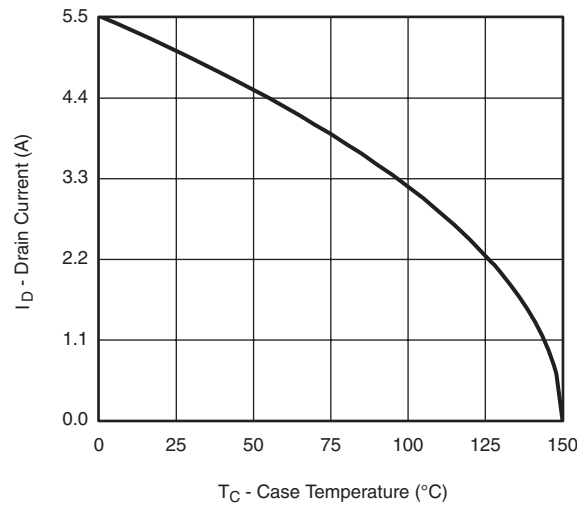
Gate Charge



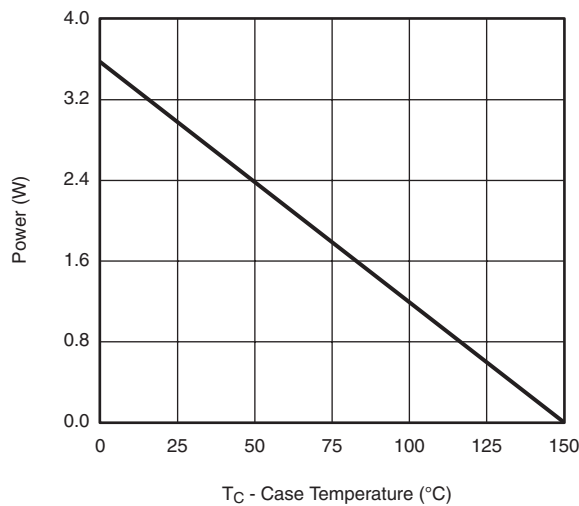
On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient*** $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified**Safe Operating Area**

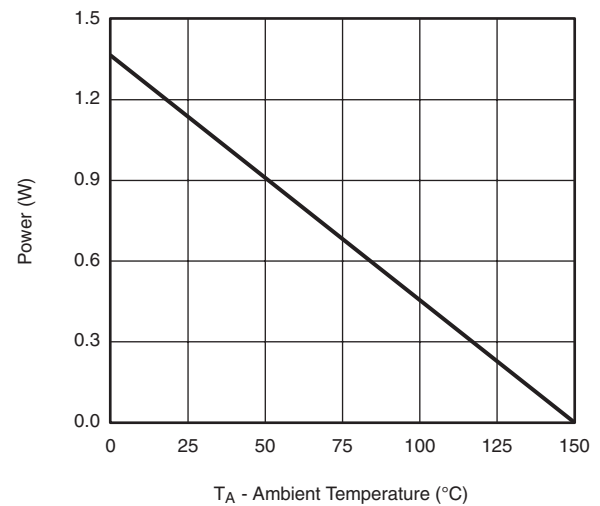
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*

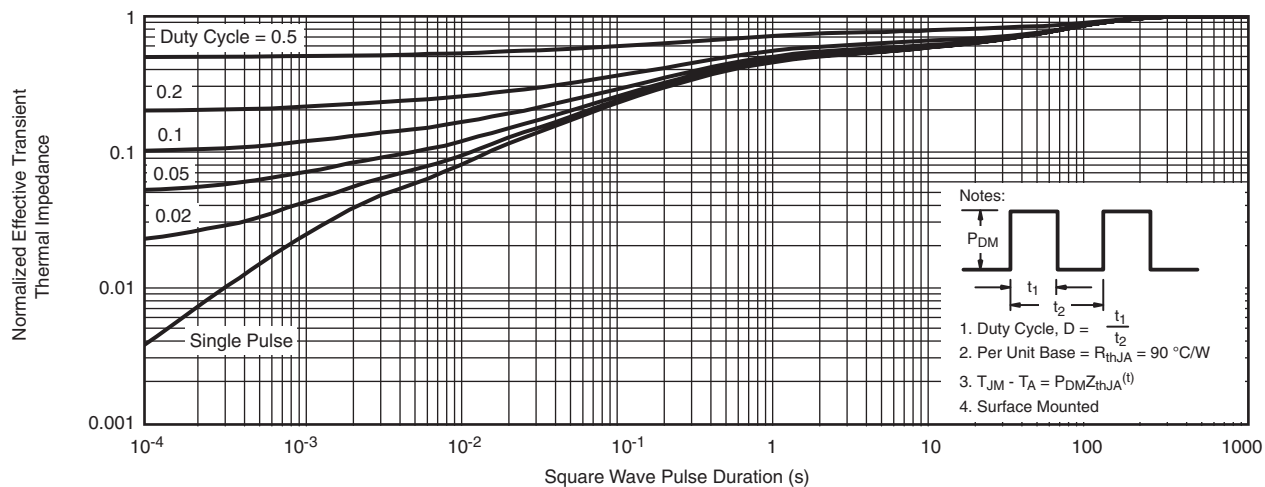
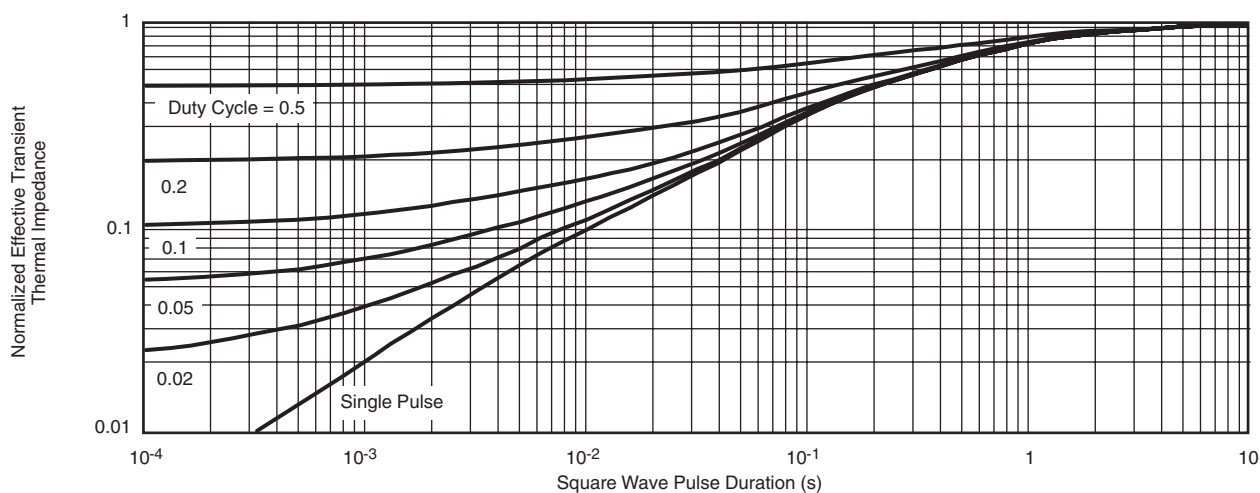


Power, Junction-to-Foot



Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Foot**

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